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dsPIC33EPXXGS50X FAMILY

16-Bit Digital Signal Controllers for Digital Power Applications with Interconnected High-Speed PWM, ADC, PGA and Comparators

Operating Conditions

- 3.0V to 3.6V, -40°C to +85°C, DC to 70 MIPS
- 3.0V to 3.6V, -40°C to +125°C, DC to 60 MIPS

Flash Architecture

- Dual Partition Flash Program Memory with Live Update (64-Kbyte devices):
  - Supports programming while operating
  - Supports partition soft swap

Core: 16-Bit dsPIC33E CPU

- Code-Efficient (C and Assembly) Architecture
- Two 40-Bit Wide Accumulators
- Single-Cycle (MAC/MPY) with Dual Data Fetch
- Single-Cycle Mixed-Sign MUL Plus Hardware Divide
- 32-Bit Multiply Support
- Two Additional Working Register Sets (reduces context switching)

Clock Management

- ±0.9% Internal Oscillator
- Programmable PLLs and Oscillator Clock Sources
- Fail-Safe Clock Monitor (FSCM)
- Independent Watchdog Timer (WDT)
- Fast Wake-up and Start-up

Power Management

- Low-Power Management modes (Sleep, Idle, Doze)
- Integrated Power-on Reset and Brown-out Reset
- 0.5 mA/MHz Dynamic Current (typical)
- 10 µA I_{PD} Current (typical)

High-Speed PWM

- Five PWM Generators (two outputs per generator)
- Individual Time Base and Duty Cycle for each PWM
- 1.04 ns PWM Resolution (frequency, duty cycle, dead time and phase)
- Supports Center-Aligned, Redundant, Complementary and True Independent Output modes
- Independent Fault and Current-Limit Inputs
- Output Override Control
- PWM Support for AC/DC, DC/DC, Inverters, PFC and Lighting

Advanced Analog Features

- High-Speed ADC module:
  - 12-bit with 4 dedicated SAR ADC cores and one shared SAR ADC core
  - Configurable resolution (up to 12-bit) for each ADC core
  - Up to 3.25 Msps conversion rate per channel at 12-bit resolution
  - 12 to 22 single-ended inputs
  - Dedicated result buffer for each analog channel
  - Flexible and independent ADC trigger sources
  - Two digital comparators
  - Two oversampling filters for increased resolution
- Four Rail-to-Rail Comparators with Hysteresis:
  - Dedicated 12-bit Digital-to-Analog Converter (DAC) for each analog comparator
  - Up to two DAC reference outputs
  - Up to two external reference inputs
- Two Programmable Gain Amplifiers:
  - Single-ended or independent ground reference
  - Five selectable gains (4x, 8x, 16x, 32x and 64x)
  - 40 MHz gain bandwidth

Interconnected SMPS Peripherals

- Reduces CPU Interaction to Improve Performance
- Flexible PWM Trigger Options for ADC Conversions
- High-Speed Comparator Truncates PWM (15 ns typical):
  - Supports Cycle-by-Cycle Current mode control
  - Current Reset mode (variable frequency)

Timers/Output Compare/Input Capture

- Five 16-Bit and up to Two 32-Bit Timers/Counters
- Four Output Compare (OC) modules, Configurable as Timers/Counters
- Four Input Capture (IC) modules

Communication Interfaces

- Two UART modules (15 Mbps):
  - Supports LIN/J2602 protocols and IrDA®
- Two 4-Wire SPI modules (15 Mbps)
- Two I^2C modules (up to 1 Mbaud) with SMBus Support

Input/Output

- Constant-Current Source (10 µA nominal)
- Sink/Source up to 12mA/15mA, respectively; Pin-Specific for Standard VOH/VOL
- 5V Tolerant Pins
- Selectable, Open-Drain Pull-ups and Pull-Downs
- External Interrupts on All I/O Pins
- Peripheral Pin Select (PPS) to allow Function Remap with Six Virtual I/Os

Qualification and Class B Support

- AEC-Q100 REVG (Grade 1, -40°C to +125°C)
- Class B Safety Library, IEC 60730
- The 6x6x0.5 mm UQFN Package is Designed and Optimized to ease IPC9592B 2nd Level Temperature Cycle Qualification

Debugger Development Support

- In-Circuit and In-Application Programming
- Five Program and Three Complex Data Breakpoints
- IEEE 1149.2 Compatible (JTAG) Boundary Scan
- Trace and Run-Time Watch

Device	Pins	Program Memory Bytes	RAM (Bytes)	General Purpose I/O (GPIO)	Remappable Peripherals								12-Bit ADC						Packages
					Timers(1)	Input Capture	Output Compare	UART	SPI	PWM(2)	External Interrupts(3)	Reference Clock	I^2C	Analog Inputs	S&H Circuits	PGA	Analog Comparator	DAC Output	Constant-Current Source	
dsPIC33EP16GS502	28	16K	2K	21	5	4	4	2	2	5x2	3	1	2	12	5	2	4	1	1	SOIC, QFN-S, UQFN
dsPIC33EP32GS502	28	32K	4K	21	5	4	4	2	2	5x2	3	1	2	12	5	2	4	1	1	
dsPIC33EP64GS502	28	64K	8K	21	5	4	4	2	2	5x2	3	1	2	12	5	2	4	1	1	
dsPIC33EP16GS504	44	16K	2K	35	5	4	4	2	2	5x2	3	1	2	19	5	2	4	1	1	QFN, TQFP
dsPIC33EP32GS504	44	32K	4K	35	5	4	4	2	2	5x2	3	1	2	19	5	2	4	1	1	
dsPIC33EP64GS504	44	64K	8K	35	5	4	4	2	2	5x2	3	1	2	19	5	2	4	1	1	
dsPIC33EP16GS505	48	16K	2K	35	5	4	4	2	2	5x2	3	1	2	19	5	2	4	1	1	TQFP
dsPIC33EP32GS505	48	32K	4K	35	5	4	4	2	2	5x2	3	1	2	19	5	2	4	1	1	
dsPIC33EP64GS505	48	64K	8K	35	5	4	4	2	2	5x2	3	1	2	19	5	2	4	1	1	
dsPIC33EP16GS506	64	16K	2K	53	5	4	4	2	2	5x2	4	1	2	22	5	2	4	2	1	TQFP
dsPIC33EP32GS506	64	32K	4K	53	5	4	4	2	2	5x2	4	1	2	22	5	2	4	2	1	
dsPIC33EP64GS506	64	64K	8K	53	5	4	4	2	2	5x2	4	1	2	22	5	2	4	2	1	

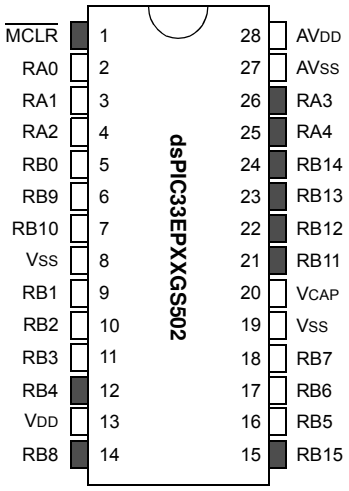
Note 1: The external clock for Timer1, Timer2 and Timer3 is remappable.

2: PWM4 and PWM5 are remappable on all devices except the 64-pin devices.

3: External interrupts, INT0 and INT4, are not remappable.

Pin Diagrams

28-Pin SOIC

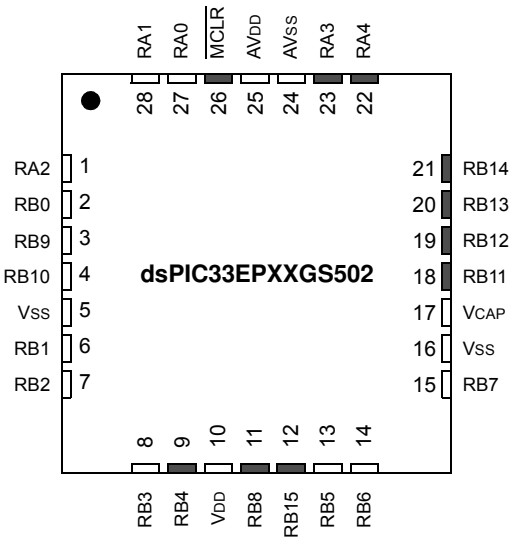


Pin	Pin Function	Pin	Pin Function
1	MCLR	15	PGEC3/SCL2/**RP47**/RB15
2	AN0/PGA1P1/CMP1A/RA0	16	TDO/AN19/PGA2N2/**RP37**/RB5
3	AN1/PGA1P2/PGA2P1/CMP1B/RA1	17	PGED1/TDI/AN20/SCL1/**RP38**/RB6
4	AN2/PGA1P3/PGA2P2/CMP1C/CMP2A/RA2	18	PGEC1/AN21/SDA1/**RP39**/RB7
5	AN3/PGA2P3/CMP1D/CMP2B/**RP32**/RB0	19	VSS
6	AN4/CMP2C/CMP3A/ISRC4/**RP41**/RB9	20	VCAP
7	AN5/CMP2D/CMP3B/ISRC3/**RP42**/RB10	21	TMS/PWM3H/**RP43**/RB11
8	Vss	22	TCK/PWM3L/**RP44**/**R**B12
9	OSC1/CLKI/AN6/CMP3C/CMP4A/ISRC2/**RP33**/RB1	23	PWM2H/**RP45**/RB13
10	OSC2/CLKO/AN7/PGA1N2/CMP3D/CMP4B/**RP34**/RB2	24	PWM2L/**RP46**/RB14
11	PGED2/AN18/DACOUT1/INT0/**RP35**/RB3	25	PWM1H/RA4
12	PGEC2/ADTRG31/EXTREF1/RP36/RB4	26	PWM1L/RA3
13	VDD	27	AVSS
14	PGED3/SDA2/FLT31/RP40/RB8	28	AVDD

Legend: **Shaded pins** are up to 5 VDC tolerant.
RPn represents remappable peripheral functions. See Table 10-1 and Table 10-2 for the complete list of remappable sources.

Pin Diagrams (Continued)

28-Pin QFN-S, UQFN

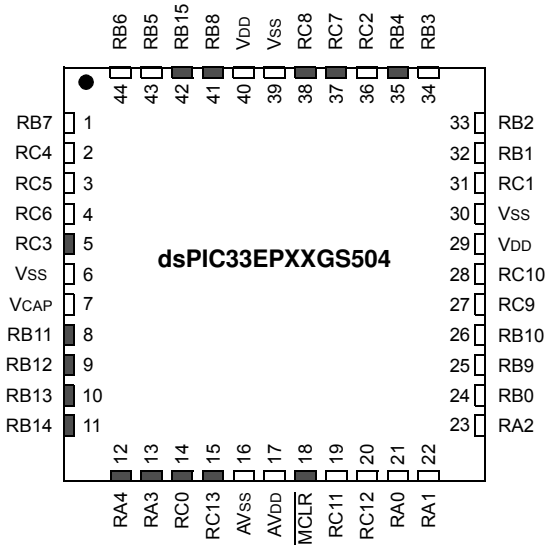


Pin	Pin Function	Pin	Pin Function
1	AN2/PGA1P3/PGA2P2/CMP1C/CMP2A/RA2	15	PGEC1/AN21/SDA1/**RP39**/RB7
2	AN3/PGA2P3/CMP1D/CMP2B/**RP32**/RB0	16	VSS
3	AN4/CMP2C/CMP3A/ISRC4/**RP41**/RB9	17	VCAP
4	AN5/CMP2D/CMP3B/ISRC3/**RP42**/RB10	18	TMS/PWM3H/**RP43**/RB11
5	Vss	19	TCK/PWM3L/**RP44**/RB12
6	OSC1/CLKI/AN6/CMP3C/CMP4A/ISRC2/**RP33**/RB1	20	PWM2H/**RP45**/RB13
7	OSC2/CLKO/AN7/PGA1N2/CMP3D/CMP4B/**RP34**/RB2	21	PWM2L/**RP46**/RB14
8	PGED2/AN18/DACOUT1/INT0/**RP35**/RB3	22	PWM1H/RA4
9	PGEC2/ADTRG31/EXTREF1/RP36/RB4	23	PWM1L/RA3
10	VDD	24	AVSS
11	PGED3/SDA2/FLT31/RP40/RB8	25	AVDD
12	PGEC3/SCL2/**RP47**/RB15	26	MCLR
13	TDO/AN19/PGA2N2/**RP37**/RB5	27	AN0/PGA1P1/CMP1A/RA0
14	PGED1/TDI/AN20/SCL1/**RP38**/RB6	28	AN1/PGA1P2/PGA2P1/CMP1B/RA1

Legend: **Shaded pins** are up to 5 VDC tolerant.
RPn represents remappable peripheral functions. See Table 10-1 and Table 10-2 for the complete list of remappable sources.

Pin Diagrams (Continued)

44-Pin QFN

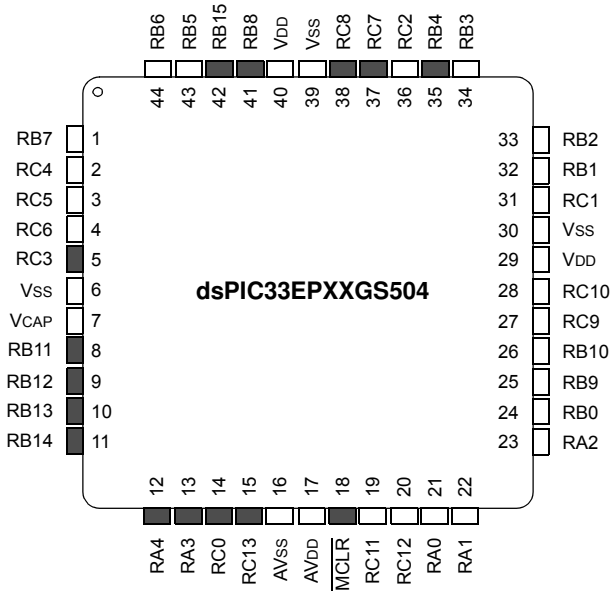


Pin	Pin Function	Pin	Pin Function
1	PGEC1/AN21/SDA1/**RP39**/RB7	23	AN2/PGA1P3/PGA2P2/CMP1C/CMP2A/RA2
2	AN1ALT/**RP52**/RC4	24	AN3/PGA2P3/CMP1D/CMP2B/**RP32**/RB0
3	AN0ALT/**RP53**/RC5	25	AN4/CMP2C/CMP3A/ISRC4/**RP41**/RB9
4	AN17/**RP54**/RC6	26	AN5/CMP2D/CMP3B/ISRC3/**RP42**/RB10
5	**RP51**/RC3	27	AN11/PGA1N3/**RP57**/RC9
6	VSS	28	AN10/PGA1P4/EXTREF2/**RP58**/RC10
7	VCAP	29	VDD
8	TMS/PWM3H/**RP43**/RB11	30	VSS
9	TCK/PWM3L/**RP44**/RB12	31	AN8/PGA2P4/CMP4C/**RP49**/RC1
10	PWM2H/**RP45**/RB13	32	OSC1/CLKI/AN6/CMP3C/CMP4A/ISRC2/**RP33**/RB1
11	PWM2L/**RP46**/RB14	33	OSC2/CLKO/AN7/PGA1N2/CMP3D/CMP4B/**RP34**/RB2
12	PWM1H/RA4	34	PGED2/AN18/DACOUT1/INT0/**RP35**/RB3
13	PWM1L/RA3	35	PGEC2/ADTRG31/**RP36**/RB4
14	FLT12/**RP48**/RC0	36	AN9/CMP4D/EXTREF1/**RP50** /RC2
15	FLT11/**RP61**/RC13	37	ASDA1/**RP55**/RC7
16	AVSS	38	ASCL1/**RP56**/RC8
17	AVDD	39	VSS
18	$\overline{\text{MCLR}}$	40	VDD
19	AN12/ISRC1/**RP59**/RC11	41	PGED3/SDA2/FLT31/**RP40**/RB8
20	AN14/PGA2N3/**RP60**/RC12	42	PGEC3/SCL2/**RP47**/RB15
21	AN0/PGA1P1/CMP1A/RA0	43	TDO/AN19/PGA2N2/**RP37**/RB5
22	AN1/PGA1P2/PGA2P1/CMP1B/RA1	44	PGED1/TDI/AN20/SCL1/**RP38**/RB6

Legend: **Shaded pins** are up to 5 VDC tolerant.
RPn represents remappable peripheral functions. See Table 10-1 and Table 10-2 for the complete list of remappable sources.

Pin Diagrams (Continued)

44-Pin TQFP

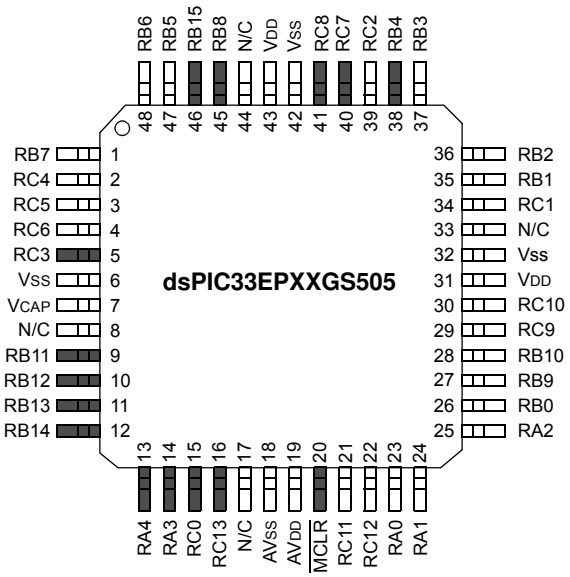


Pin	Pin Function	Pin	Pin Function
1	PGEC1/AN21/SDA1/**RP39**/RB7	23	AN2/PGA1P3/PGA2P2/CMP1C/CMP2A/RA2
2	AN1ALT/**RP52**/RC4	24	AN3/PGA2P3/CMP1D/CMP2B/**RP32**/RB0
3	AN0ALT/**RP53**/RC5	25	AN4/CMP2C/CMP3A/ISRC4/**RP41**/RB9
4	AN17/**RP54**/RC6	26	AN5/CMP2D/CMP3B/ISRC3/**RP42**/RB10
5	**RP51**/RC3	27	AN11/PGA1N3/**RP57**/RC9
6	VSS	28	AN10/PGA1P4/EXTREF2/**RP58**/RC10
7	VCAP	29	VDD
8	TMS/PWM3H/**RP43**/RB11	30	VSS
9	TCK/PWM3L/**RP44**/RB12	31	AN8/PGA2P4/CMP4C/**RP49**/RC1
10	PWM2H/**RP45**/RB13	32	OSC1/CLKI/AN6/CMP3C/CMP4A/ISRC2/**RP33**/RB1
11	PWM2L/**RP46**/RB14	33	OSC2/CLKO/AN7/PGA1N2/CMP3D/CMP4B/**RP34**/RB2
12	PWM1H/RA4	34	PGED2/AN18/DACOUT1/INT0/**RP35**/RB3
13	PWM1L/RA3	35	PGEC2/ADTRG31/**RP36**/RB4
14	FLT12/**RP48**/RC0	36	AN9/CMP4D/EXTREF1/**RP50** /RC2
15	FLT11/**RP61**/RC13	37	ASDA1/**RP55**/RC7
16	AVSS	38	ASCL1/**RP56**/RC8
17	AVDD	39	VSS
18	$\overline{\text{MCLR}}$	40	VDD
19	AN12/ISRC1/**RP59**/RC11	41	PGED3/SDA2/FLT31/**RP40**/RB8
20	AN14/PGA2N3/**RP60**/RC12	42	PGEC3/SCL2/**RP47**/RB15
21	AN0/PGA1P1/CMP1A/RA0	43	TDO/AN19/PGA2N2/**RP37**/RB5
22	AN1/PGA1P2/PGA2P1/CMP1B/RA1	44	PGED1/TDI/AN20/SCL1/**RP38**/RB6

Legend: **Shaded pins** are up to 5 VDC tolerant.
RPn represents remappable peripheral functions. See Table 10-1 and Table 10-2 for the complete list of remappable sources.

Pin Diagrams (Continued)

48-Pin TQFP

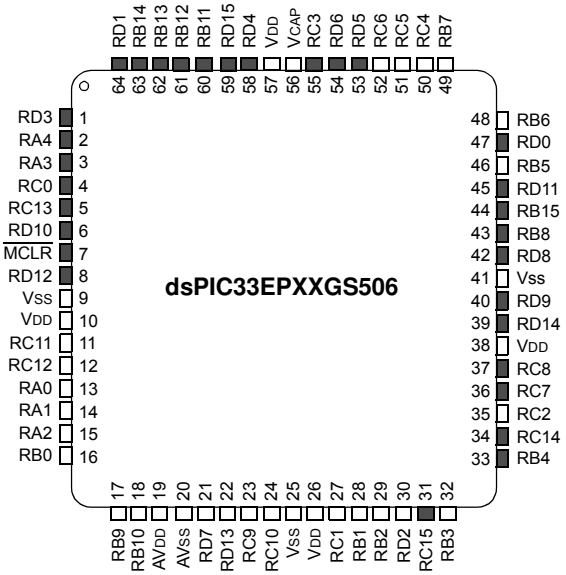


Pin	Pin Function	Pin	Pin Function
1	PGEC1/AN21/SDA1/**RP39**/RB7	25	AN2/PGA1P3/PGA2P2/CMP1C/CMP2A/RA2
2	AN1ALT/**RP52**/RC4	26	AN3/PGA2P3/CMP1D/CMP2B/**RP32**/RB0
3	AN0ALT/**RP53**/RC5	27	AN4/CMP2C/CMP3A/ISRC4/**RP41**/RB9
4	AN17/**RP54**/RC6	28	AN5/CMP2D/CMP3B/ISRC3/**RP42**/RB10
5	**RP51**/RC3	29	AN11/PGA1N3/**RP57**/RC9
6	VSS	30	AN10/PGA1P4/EXTREF2/**RP58**/RC10
7	VCAP	31	VDD
8	N/C	32	VSS
9	TMS/PWM3H/**RP43**/RB11	33	N/C
10	TCK/PWM3L/**RP44**/RB12	34	AN8/PGA2P4/CMP4C/**RP49**/RC1
11	PWM2H/**RP45**/RB13	35	OSC1/CLKI/AN6/CMP3C/CMP4A/ISRC2/**RP33**/RB1
12	PWM2L/**RP46**/RB14	36	OSC2/CLKO/AN7/PGA1N2/CMP3D/CMP4B/**RP34**/RB2
13	PWM1H/RA4	37	PGED2/AN18/DACOUT1/INT0/**RP35**/RB3
14	PWM1L/RA3	38	PGEC2/ADTRG31/**RP36**/RB4
15	FLT12/**RP48**/RC0	39	AN9/CMP4D/EXTREF1/**RP50** /RC2
16	FLT11/**RP61**/RC13	40	ASDA1/**RP55**/RC7
17	N/C	41	ASCL1/**RP56**/RC8
18	AVSS	42	VSS
19	AVDD	43	VDD
20	$\overline{\text{MCLR}}$	44	N/C
21	AN12/ISRC1/**RP59**/RC11	45	PGED3/SDA2/FLT31/**RP40**/RB8
22	AN14/PGA2N3/**RP60**/RC12	46	PGEC3/SCL2/**RP47**/RB15
23	AN0/PGA1P1/CMP1A/RA0	47	TDO/AN19/PGA2N2/**RP37**/RB5
24	AN1/PGA1P2/PGA2P1/CMP1B/RA1	48	PGED1/TDI/AN20/SCL1/**RP38**/RB6

Legend: **Shaded pins** are up to 5 VDC tolerant.
RPn represents remappable peripheral functions. See Table 10-1 and Table 10-2 for the complete list of remappable sources.

Pin Diagrams (Continued)

64-Pin TQFP



Pin	Pin Function	Pin	Pin Function
1	PWM4L/RD3	33	PGEC2/ADTRG31/**RP36**/RB4
2	PWM1H/RA4	34	**RP62**/RC14
3	PWM1L/RA3	35	AN9/CMP4D/EXTREF1/**RP50**/RC2
4	FLT12/**RP48**/RC0	36	ASDA1/**RP55**/RC7
5	FLT11/**RP61**/RC13	37	ASCL1/**RP56**/RC8
6	FLT10/RD10	38	VDD
7	$\overline{\text{MCLR}}$	39	RD14
8	FLT9/T5CK/RD12	40	RD9
9	VSS	41	VSS
10	VDD	42	RD8
11	AN12/ISRC1/**RP59**/RC11	43	PGED3/SDA2/FLT31/**RP40**/RB8
12	AN14/PGA2N3/**RP60**/RC12	44	PGEC3/SCL2/**RP47**/RB15
13	AN0/PGA1P1/CMP1A/RA0	45	INT4/RD11
14	AN1/PGA1P2/PGA2P1/CMP1B/RA1	46	TDO/AN19/PGA2N2/**RP37**/RB5
15	AN2/PGA1P3/PGA2P2/CMP1C/CMP2A/RA2	47	T4CK/RD0
16	AN3/PGA2P3/CMP1D/CMP2B/**RP32**/RB0	48	PGED1/TDI/AN20/SCL1/**RP38**/RB6
17	AN4/CMP2C/CMP3A/ISRC4/**RP41**/RB9	49	PGEC1/AN21/SDA1/**RP39**/RB7
18	AN5/CMP2D/CMP3B/ISRC3/**RP42**/RB10	50	AN1ALT/**RP52**/RC4
19	AVDD	51	AN0ALT/**RP53**/RC5
20	AVSS	52	AN17/**RP54**/RC6
21	AN15/RD7	53	RD5
22	AN13/DACOUT2/RD13	54	PWM5H/RD6
23	AN11/PGA1N3/**RP57**/RC9	55	PWM5L/**RP51**/RC3
24	AN10/PGA1P4/EXTREF2/**RP58**/RC10	56	VCAP
25	VSS	57	VDD
26	VDD	58	RD4
27	AN8/PGA2P4/CMP4C/**RP49**/RC1	59	RD15
28	OSC1/CLKI/AN6/CMP3C/CMP4A/ISRC2/**RP33**/RB1	60	TMS/PWM3H/**RP43**/RB11
29	OSC2/CLKO/AN7/PGA1N2/CMP3D/CMP4B/**RP34**/RB2	61	TCK/PWM3L/**RP44**/RB12
30	AN16/RD2	62	PWM2H/**RP45**/RB13
31	ASDA2/**RP63**/RC15	63	PWM2L/**RP46**/RB14
32	PGED2/AN18/DACOUT1/ASCL2/INT0/RP35/RB3	64	PWM4H/RD1

Legend: **Shaded pins** are up to 5 VDC tolerant.
RPn represents remappable peripheral functions. See Table 10-1 and Table 10-2 for the complete list of remappable sources.

Table of Contents

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To determine if an errata sheet exists for a particular device, please check with one of the following:

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When contacting a sales office, please specify which device, revision of silicon and data sheet (include literature number) you are using.

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1.0 DEVICE OVERVIEW

Note 1: This data sheet summarizes the features of the dsPIC33EPXXGS50X family of devices. It is not intended to be a comprehensive resource. To complement the information in this data sheet, refer to the related section of the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

This document contains device-specific information for the dsPIC33EPXXGS50X Digital Signal Controller (DSC) devices.

dsPIC33EPXXGS50X devices contain extensive Digital Signal Processor (DSP) functionality with a high-performance, 16-bit MCU architecture.

Figure 1-1 shows a general block diagram of the core and peripheral modules. Table 1-1 lists the functions of the various pins shown in the pinout diagrams.

FIGURE 1-1: dsPIC33EPXXGS50X FAMILY BLOCK DIAGRAM

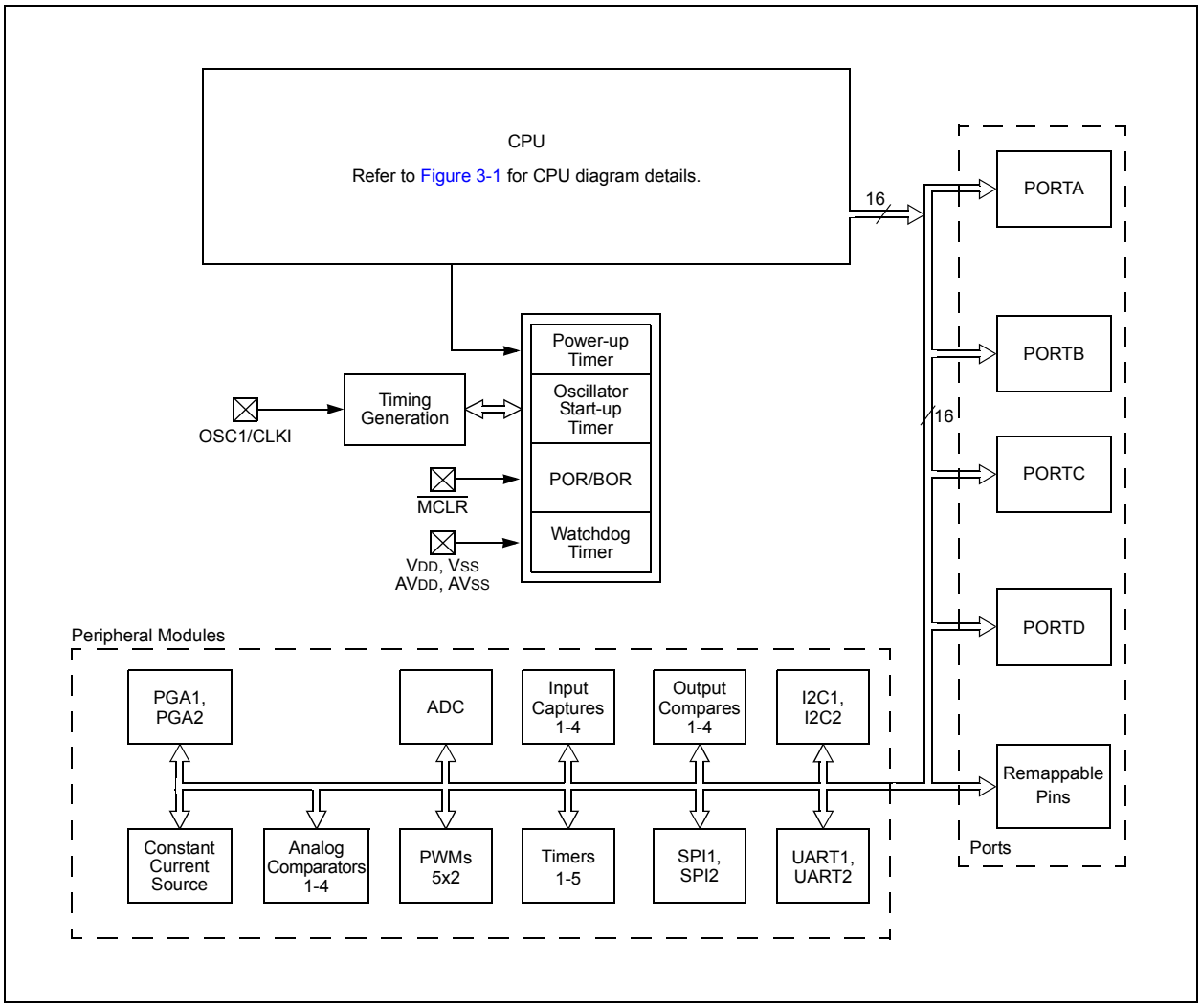


TABLE 1-1: PINOUT I/O DESCRIPTIONS

Pin Name[1]	Pin Type	Buffer Type	PPS	Description
AN0-AN21	I	Analog	No	Analog input channels.
AN0ALT-AN1ALT	I	Analog	No	Alternate analog input channels.
CLKI	I	ST/ CMOS	No	External clock source input. Always associated with OSC1 pin function.
CLKO	O	—	No	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes. Always associated with OSC2 pin function.
OSC1	I	ST/ CMOS	No	Oscillator crystal input. ST buffer when configured in RC mode; CMOS otherwise.
OSC2	I/O	—	No	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes.
REFCLKO	O	—	Yes	Reference clock output.
IC1-IC4	I	ST	Yes	Capture Inputs 1 through 4.
OCFA	I	ST	Yes	Compare Fault A input (for compare channels).
OC1-OC4	O	—	Yes	Compare Outputs 1 through 4.
INT0	I	ST	No	External Interrupt 0.
INT1	I	ST	Yes	External Interrupt 1.
INT2	I	ST	Yes	External Interrupt 2.
INT4	I	ST	No	External Interrupt 4.
RA0-RA4	I/O	ST	No	PORTA is a bidirectional I/O port.
RB0-RB15	I/O	ST	No	PORTB is a bidirectional I/O port.
RC0-RC15	I/O	ST	No	PORTC is a bidirectional I/O port.
RD0-RD15	I/O	ST	No	PORTD is a bidirectional I/O port.
T1CK	I	ST	Yes	Timer1 external clock input.
T2CK	I	ST	Yes	Timer2 external clock input.
T3CK	I	ST	Yes	Timer3 external clock input.
T4CK	I	ST	No	Timer4 external clock input.
T5CK	I	ST	No	Timer5 external clock input.
$\overline{U1CTS}$	I	ST	Yes	UART1 Clear-to-Send.
$\overline{U1RTS}$	O	—	Yes	UART1 Request-to-Send.
U1RX	I	ST	Yes	UART1 receive.
U1TX	O	—	Yes	UART1 transmit.
BCLK1	O	ST	Yes	UART1 IrDA® baud clock output.
$\overline{U2CTS}$	I	ST	Yes	UART2 Clear-to-Send.
$\overline{U2RTS}$	O	—	Yes	UART2 Request-to-Send.
U2RX	I	ST	Yes	UART2 receive.
U2TX	O	—	Yes	UART2 transmit.
BCLK2	O	ST	Yes	UART2 IrDA baud clock output.
SCK1	I/O	ST	Yes	Synchronous serial clock input/output for SPI1.
SDI1	I	ST	Yes	SPI1 data in.
$\overline{SDO1}$	O	—	Yes	SPI1 data out.
$\overline{SS1}$	I/O	ST	Yes	SPI1 slave synchronization or frame pulse I/O.
SCK2	I/O	ST	Yes	Synchronous serial clock input/output for SPI2.
SDI2	I	ST	Yes	SPI2 data in.
$\overline{SDO2}$	O	—	Yes	SPI2 data out.
$\overline{SS2}$	I/O	ST	Yes	SPI2 slave synchronization or frame pulse I/O.

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
PPS = Peripheral Pin Select; TTL = TTL input buffer

1: Not all pins are available in all packages variants. See the **"Pin Diagrams"** section for pin availability.

2: These pins are dedicated on 64-pin devices.

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name[1]	Pin Type	Buffer Type	PPS	Description
SCL1	I/O	ST	No	Synchronous serial clock input/output for I2C1.
SDA1	I/O	ST	No	Synchronous serial data input/output for I2C1.
ASCL1	I/O	ST	No	Alternate synchronous serial clock input/output for I2C1.
ASDA1	I/O	ST	No	Alternate synchronous serial data input/output for I2C1.
SCL2	I/O	ST	No	Synchronous serial clock input/output for I2C2.
SDA2	I/O	ST	No	Synchronous serial data input/output for I2C2.
ASCL2	I/O	ST	No	Alternate synchronous serial clock input/output for I2C2.
ASDA2	I/O	ST	No	Alternate synchronous serial data input/output for I2C2.
TMS	I	ST	No	JTAG Test mode select pin.
TCK	I	ST	No	JTAG test clock input pin.
TDI	I	ST	No	JTAG test data input pin.
TDO	O	—	No	JTAG test data output pin.
FLT1-FLT8	I	ST	Yes	PWM Fault Inputs 1 through 8.
FLT9-FLT12	I	ST	No	PWM Fault Inputs 9 through 12.
FLT31	I	ST	No	PWM Fault Input 31 (Class B Fault).
PWM1L-PWM3L	O	—	No	PWM Low Outputs 1 through 3.
PWM1H-PWM3H	O	—	No	PWM High Outputs 1 through 3.
PWM4L-PWM5L[2]	O	—	Yes	PWM Low Outputs 4 and 5.
PWM4H-PWM5H[2]	O	—	Yes	PWM High Outputs 4 and 5.
SYNCI1, SYNCI2	I	ST	Yes	PWM Synchronization Inputs 1 and 2.
SYNCO1, SYNCO2	O	—	Yes	PWM Synchronization Outputs 1 and 2.
CMP1A-CMP4A	I	Analog	No	Comparator Channels 1 through 4 A input.
CMP1B-CMP4B	I	Analog	No	Comparator Channels 1 through 4 B input.
CMP1C-CMP4C	I	Analog	No	Comparator Channels 1 through 4 C input.
CMP1D-CMP4D	I	Analog	No	Comparator Channels 1 through 4 D input.
DACOUT1, DACOUT2	O	—	No	DAC Output Voltages 1 and 2.
EXTREF1, EXTREF2	I	Analog	No	External Voltage Reference Inputs 1 and 2 for the reference DACs.
ISRC1-ISRC4	O	Analog	No	Constant-Current Outputs 1 through 4.
PGA1P1-PGA1P4	I	Analog	No	PGA1 Positive Inputs 1 through 4.
PGA1N1-PGA1N3	I	Analog	No	PGA1 Negative Inputs 1 through 3.
PGA2P1-PGA2P4	I	Analog	No	PGA2 Positive Inputs 1 through 4.
PGA2N1-PGA2N3	I	Analog	No	PGA2 Negative Inputs 1 through 3.
ADTRG31	I	ST	No	External ADC trigger source.
PGED1	I/O	ST	No	Data I/O pin for Programming/Debugging Communication Channel 1.
PGEC1	I	ST	No	Clock input pin for Programming/Debugging Communication Channel 1.
PGED2	I/O	ST	No	Data I/O pin for Programming/Debugging Communication Channel 2.
PGEC2	I	ST	No	Clock input pin for Programming/Debugging Communication Channel 2.
PGED3	I/O	ST	No	Data I/O pin for Programming/Debugging Communication Channel 3.
PGEC3	I	ST	No	Clock input pin for Programming/Debugging Communication Channel 3.

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
PPS = Peripheral Pin Select; TTL = TTL input buffer

1: Not all pins are available in all packages variants. See the **"Pin Diagrams"** section for pin availability.

2: These pins are dedicated on 64-pin devices.

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name(1)	Pin Type	Buffer Type	PPS	Description
$\overline{MCLR}$	I/P	ST	No	Master Clear (Reset) input. This pin is an active-low Reset to the device.
AVDD	P	P	No	Positive supply for analog modules. This pin must be connected at all times.
AVSS	P	P	No	Ground reference for analog modules. This pin must be connected at all times.
VDD	P	—	No	Positive supply for peripheral logic and I/O pins.
VCAP	P	—	No	CPU logic filter capacitor connection.
VSS	P	—	No	Ground reference for logic and I/O pins.

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
PPS = Peripheral Pin Select; TTL = TTL input buffer

1: Not all pins are available in all packages variants. See the **"Pin Diagrams"** section for pin availability.

2: These pins are dedicated on 64-pin devices.

2.0 GUIDELINES FOR GETTING STARTED WITH 16-BIT DIGITAL SIGNAL CONTROLLERS

Note 1: This data sheet summarizes the features of the dsPIC33EPXXGS50X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the related section of the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

2.1 Basic Connection Requirements

Getting started with the dsPIC33EPXXGS50X family requires attention to a minimal set of device pin connections before proceeding with development. The following is a list of pin names which must always be connected:

- All VDD and VSS pins
  (see **Section 2.2 "Decoupling Capacitors"**)
- All AVDD and AVSS pins
  regardless if ADC module is not used (see **Section 2.2 "Decoupling Capacitors"**)
- VCAP
  (see **Section 2.3 "CPU Logic Filter Capacitor Connection (VCAP)"**)
- $\overline{\text{MCLR}}$ pin
  (see **Section 2.4 "Master Clear (MCLR) Pin"**)
- PGECx/PGEDx pins
  used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes (see **Section 2.5 "ICSP Pins"**)
- OSC1 and OSC2 pins
  when external oscillator source is used (see **Section 2.6 "External Oscillator Pins"**)

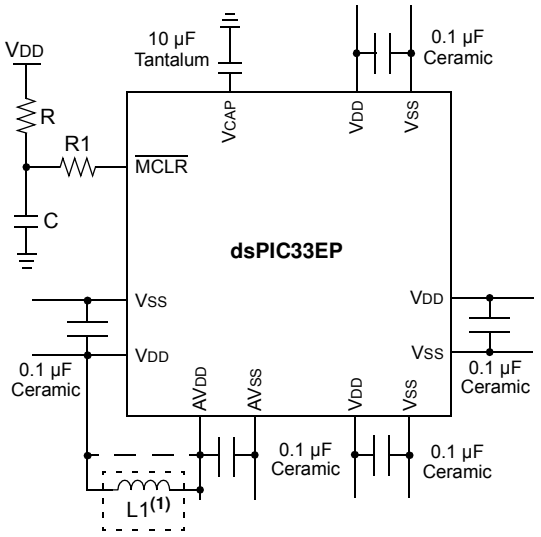
2.2 Decoupling Capacitors

The use of decoupling capacitors on every pair of power supply pins, such as VDD, VSS, AVDD and AVSS is required.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** Recommendation of 0.1 µF (100 nF), 10-20V. This capacitor should be a low-ESR and have resonance frequency in the range of 20 MHz and higher. It is recommended to use ceramic capacitors.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is within one-quarter inch (6 mm) in length.
- **Handling high-frequency noise:** If the board is experiencing high-frequency noise, above tens of MHz, add a second ceramic-type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 µF to 0.001 µF. Place this second capacitor next to the primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible. For example, 0.1 µF in parallel with 0.001 µF.
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum, thereby reducing PCB track inductance.

FIGURE 2-1: RECOMMENDED MINIMUM CONNECTION



Note 1: As an option, instead of a hard-wired connection, an inductor (L1) can be substituted between VDD and AVDD to improve ADC noise rejection. The inductor impedance should be less than 1Ω and the inductor capacity greater than 10 mA.

Where:

$$f = \frac{FCNV}{2} \quad \text{(i.e., ADC Conversion Rate/2)}$$

$$f = \frac{1}{(2\pi\sqrt{LC})}$$

$$L = \left(\frac{1}{(2\pi f\sqrt{C})}\right)^2$$

2.2.1 TANK CAPACITORS

On boards with power traces running longer than six inches in length, it is suggested to use a tank capacitor for integrated circuits including DSCs to supply a local power source. The value of the tank capacitor should be determined based on the trace resistance that connects the power supply source to the device and the maximum current drawn by the device in the application. In other words, select the tank capacitor so that it meets the acceptable voltage sag at the device. Typical values range from 4.7 µF to 47 µF.

2.3 CPU Logic Filter Capacitor Connection (VCAP)

A low-ESR (<0.5 Ω) capacitor is required on the VCAP pin, which is used to stabilize the voltage regulator output voltage. The VCAP pin must not be connected to VDD and must have a capacitor greater than 4.7 µF (10 µF is recommended), 16V connected to ground. The type can be ceramic or tantalum. See **Section 26.0 "Electrical Characteristics"** for additional information.

The placement of this capacitor should be close to the VCAP pin. It is recommended that the trace length not exceeds one-quarter inch (6 mm). See **Section 23.4 "On-Chip Voltage Regulator"** for details.

2.4 Master Clear (MCLR) Pin

The MCLR pin provides two specific device functions:

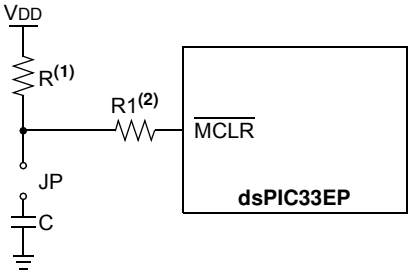
- Device Reset
- Device Programming and Debugging.

During device programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the MCLR pin. Consequently, specific voltage levels (VIH and VIL) and fast signal transitions must not be adversely affected. Therefore, specific values of R and C will need to be adjusted based on the application and PCB requirements.

For example, as shown in Figure 2-2, it is recommended that the capacitor C, be isolated from the MCLR pin during programming and debugging operations.

Place the components as shown in Figure 2-2 within one-quarter inch (6 mm) from the MCLR pin.

FIGURE 2-2: EXAMPLE OF MCLR PIN CONNECTIONS



Note 1: R ≤ 10 kΩ is recommended. A suggested starting value is 10 kΩ. Ensure that the MCLR pin VIH and VIL specifications are met.

2: R1 ≤ 470Ω will limit any current flowing into MCLR from the external capacitor, C, in the event of MCLR pin breakdown due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the MCLR pin VIH and VIL specifications are met.

2.5 ICSP Pins

The PGECx and PGEDx pins are used for ICSP and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin Voltage Input High (V_{IH}) and Voltage Input Low (V_{IL}) requirements.

Ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® PICkit™ 3, MPLAB ICD 3, or MPLAB REAL ICE™.

For more information on MPLAB ICD 2, MPLAB ICD 3 and REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site.

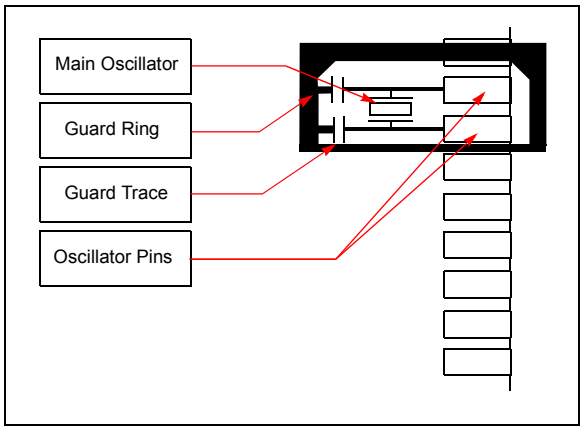
- *"Using MPLAB® ICD 3"* (poster) DS51765
- *"Multi-Tool Design Advisory"* DS51764
- *"MPLAB® REAL ICE™ In-Circuit Emulator User's Guide"* DS51616
- *"Using MPLAB® REAL ICE™ In-Circuit Emulator"* (poster) DS51749

2.6 External Oscillator Pins

Many DSCs have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator. For details, see **Section 8.0 "Oscillator Configuration"** for details.

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is shown in Figure 2-3.

FIGURE 2-3: SUGGESTED PLACEMENT OF THE OSCILLATOR CIRCUIT



2.7 Oscillator Value Conditions on Device Start-up

If the PLL of the target device is enabled and configured for the device start-up oscillator, the maximum oscillator source frequency must be limited to 3 MHz < FIN < 5.5 MHz to comply with device PLL start-up conditions. This means that if the external oscillator frequency is outside this range, the application must start-up in the FRC mode first. The default PLL settings after a POR with an oscillator frequency outside this range will violate the device operating speed.

Once the device powers up, the application firmware can initialize the PLL SFRs, CLKDIV and PLLDBF to a suitable value, and then perform a clock switch to the Oscillator + PLL clock source. Note that clock switching must be enabled in the device Configuration Word.

2.8 Unused I/Os

Unused I/O pins should be configured as outputs and driven to a logic-low state.

Alternatively, connect a 1k to 10k resistor between VSS and unused pins and drive the output to logic low.

2.9 Targeted Applications

- Power Factor Correction (PFC)
  - Interleaved PFC
  - Critical Conduction PFC
  - Bridgeless PFC
- DC/DC Converters
  - Buck, Boost, Forward, Flyback, Push-Pull
  - Half/Full-Bridge
  - Phase-Shift Full-Bridge
  - Resonant Converters
- DC/AC
  - Half/Full-Bridge Inverter
  - Resonant Inverter

Examples of typical application connections are shown in Figure 2-4 through Figure 2-6.

FIGURE 2-4: INTERLEAVED PFC

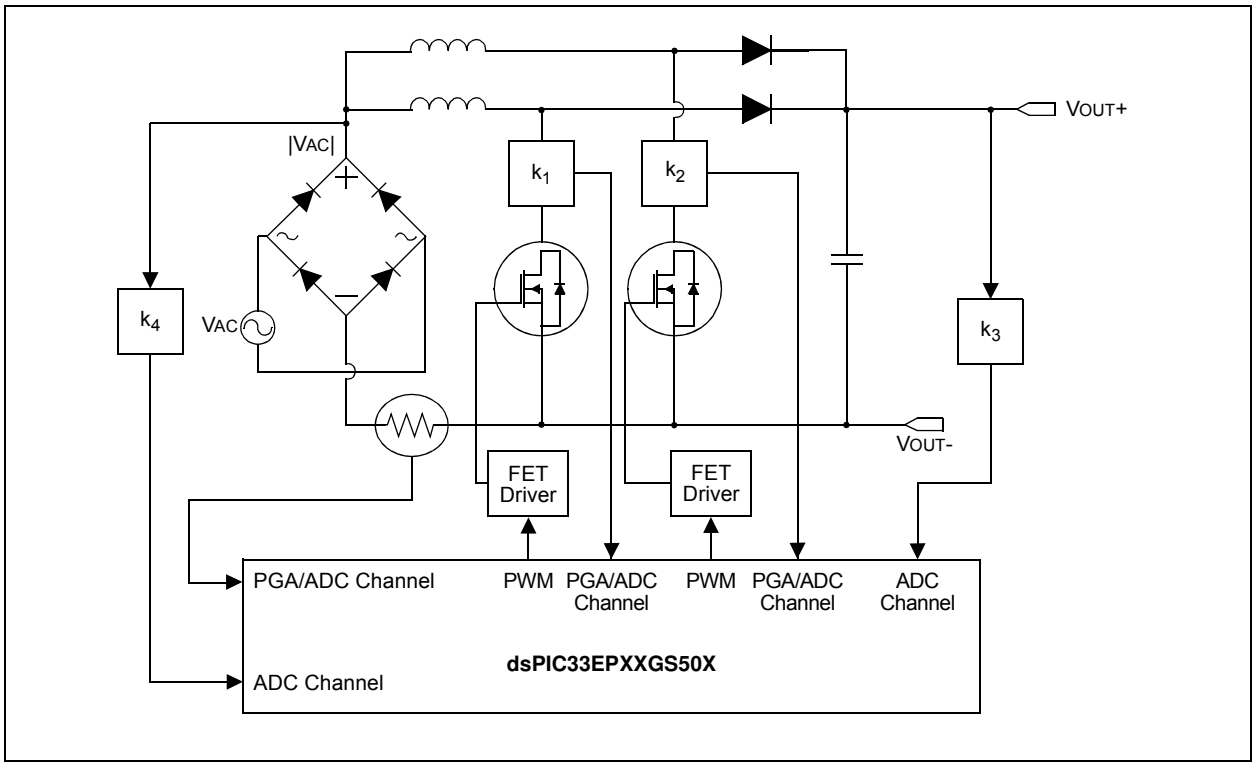


FIGURE 2-5: PHASE-SHIFTED FULL-BRIDGE CONVERTER

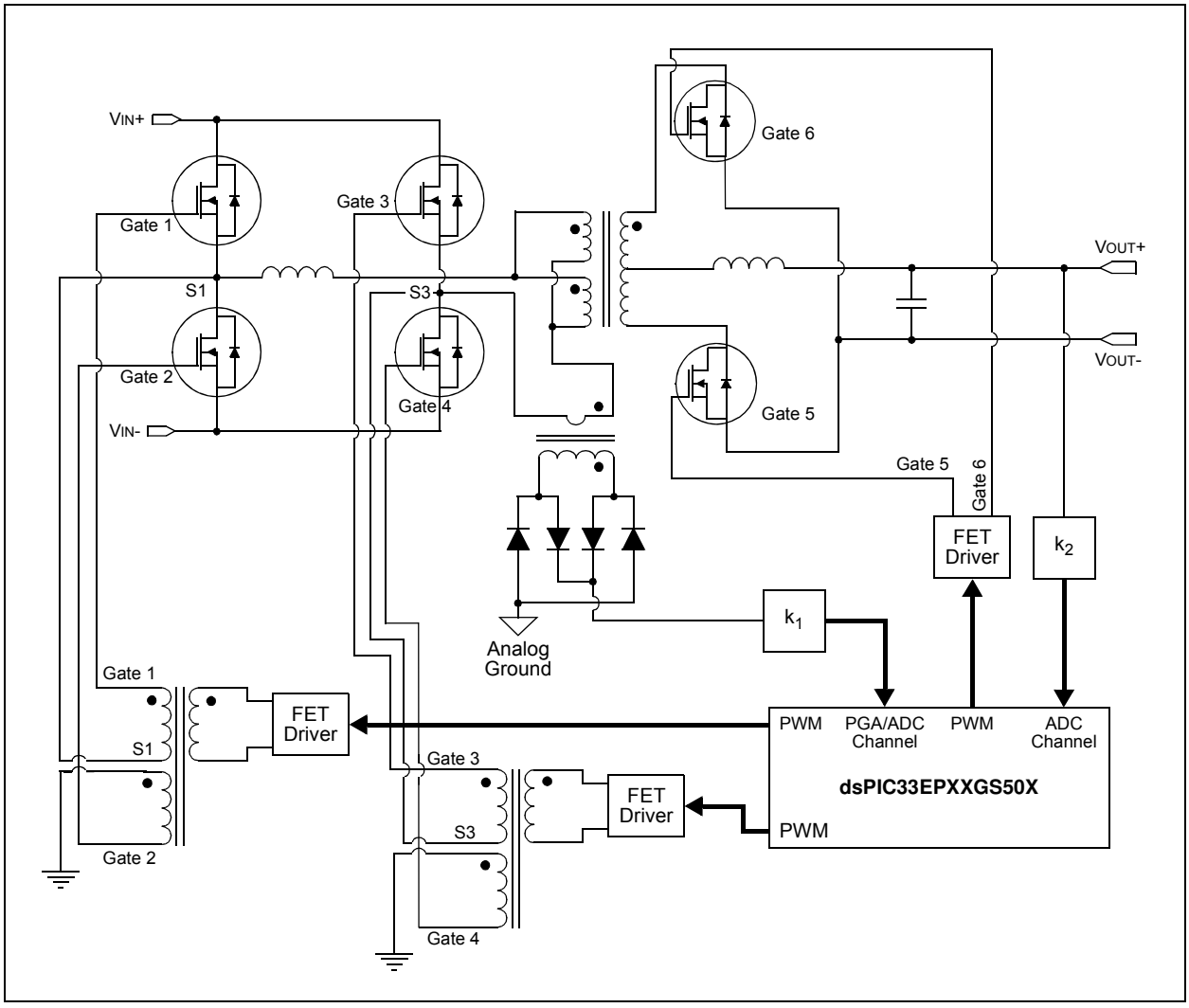
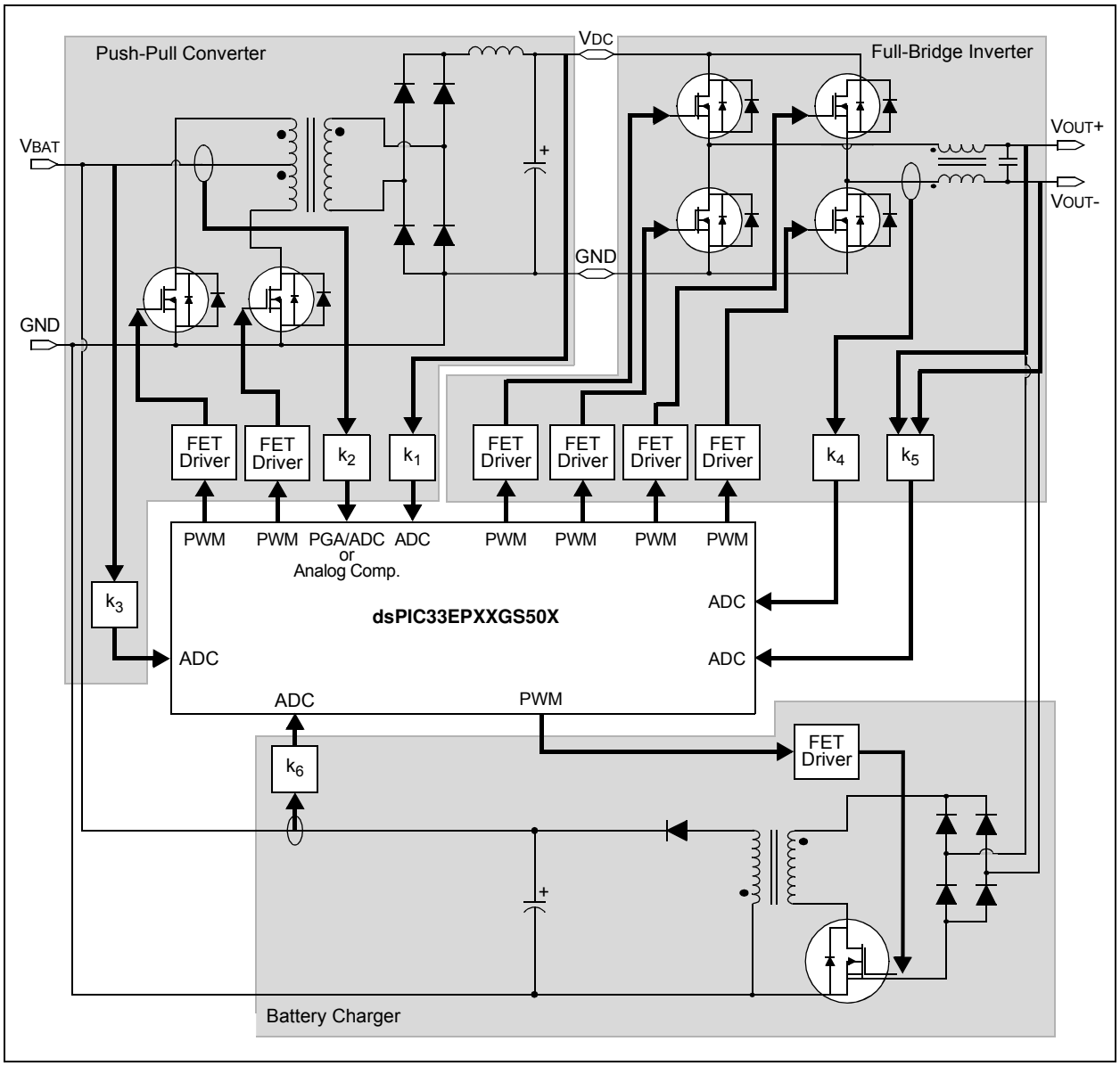


FIGURE 2-6: OFF-LINE UPS



3.0 CPU

Note 1: This data sheet summarizes the features of the dsPIC33EPXXGS50X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"CPU"** (DS70359) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXGS50X family CPU has a 16-bit (data) modified Harvard architecture with an enhanced instruction set, including significant support for Digital Signal Processing (DSP). The CPU has a 24-bit instruction word with a variable length opcode field. The Program Counter (PC) is 23 bits wide and addresses up to 4M x 24 bits of user program memory space.

An instruction prefetch mechanism helps maintain throughput and provides predictable execution. Most instructions execute in a single-cycle effective execution rate, with the exception of instructions that change the program flow, the double-word move (`MOV.D`) instruction, PSV accesses and the table instructions. Overhead-free program loop constructs are supported using the `DO` and `REPEAT` instructions, both of which are interruptible at any point.

3.1 Registers

The dsPIC33EPXXGS50X devices have sixteen, 16-bit Working registers in the programmer's model. Each of the Working registers can act as a data, address or address offset register. The 16th Working register (W15) operates as a Software Stack Pointer for interrupts and calls.

In addition, the dsPIC33EPXXGS50X devices include two Alternate Working register sets which consist of W0 through W14. The Alternate registers can be made persistent to help reduce the saving and restoring of register content during Interrupt Service Routines (ISRs). The Alternate Working registers can be assigned to a specific Interrupt Priority Level (IPL1 through IPL6) by configuring the CTXTx<2:0> bits in the FALTREG Configuration register. The Alternate Working registers can also be accessed manually by using the `CTXTSWP` instruction. The CCTXI<2:0> and MCTXI<2:0> bits in the CTXTSTAT register can be used to identify the current and most recent, manually selected Working register sets.

3.2 Instruction Set

The instruction set for dsPIC33EPXXGS50X devices has two classes of instructions: the MCU class of instructions and the DSP class of instructions. These two instruction classes are seamlessly integrated into the architecture and execute from a single execution unit. The instruction set includes many addressing modes and was designed for optimum C compiler efficiency.

3.3 Data Space Addressing

The base Data Space can be addressed as up to 4K words or 8 Kbytes, and is split into two blocks, referred to as X and Y data memory. Each memory block has its own independent Address Generation Unit (AGU). The MCU class of instructions operates solely through the X memory AGU, which accesses the entire memory map as one linear Data Space. Certain DSP instructions operate through the X and Y AGUs to support dual operand reads, which splits the data address space into two parts. The X and Y Data Space boundary is device-specific.

The upper 32 Kbytes of the Data Space memory map can optionally be mapped into Program Space (PS) at any 16K program word boundary. The program-to-Data Space mapping feature, known as Program Space Visibility (PSV), lets any instruction access Program Space as if it were Data Space. Refer to **"Data Memory"** (DS70595) in the *"dsPIC33/PIC24 Family Reference Manual"* for more details on PSV and table accesses.

On dsPIC33EPXXGS50X devices, overhead-free circular buffers (Modulo Addressing) are supported in both X and Y address spaces. The Modulo Addressing removes the software boundary checking overhead for DSP algorithms. The X AGU Circular Addressing can be used with any of the MCU class of instructions. The X AGU also supports Bit-Reversed Addressing to greatly simplify input or output data re-ordering for radix-2 FFT algorithms.

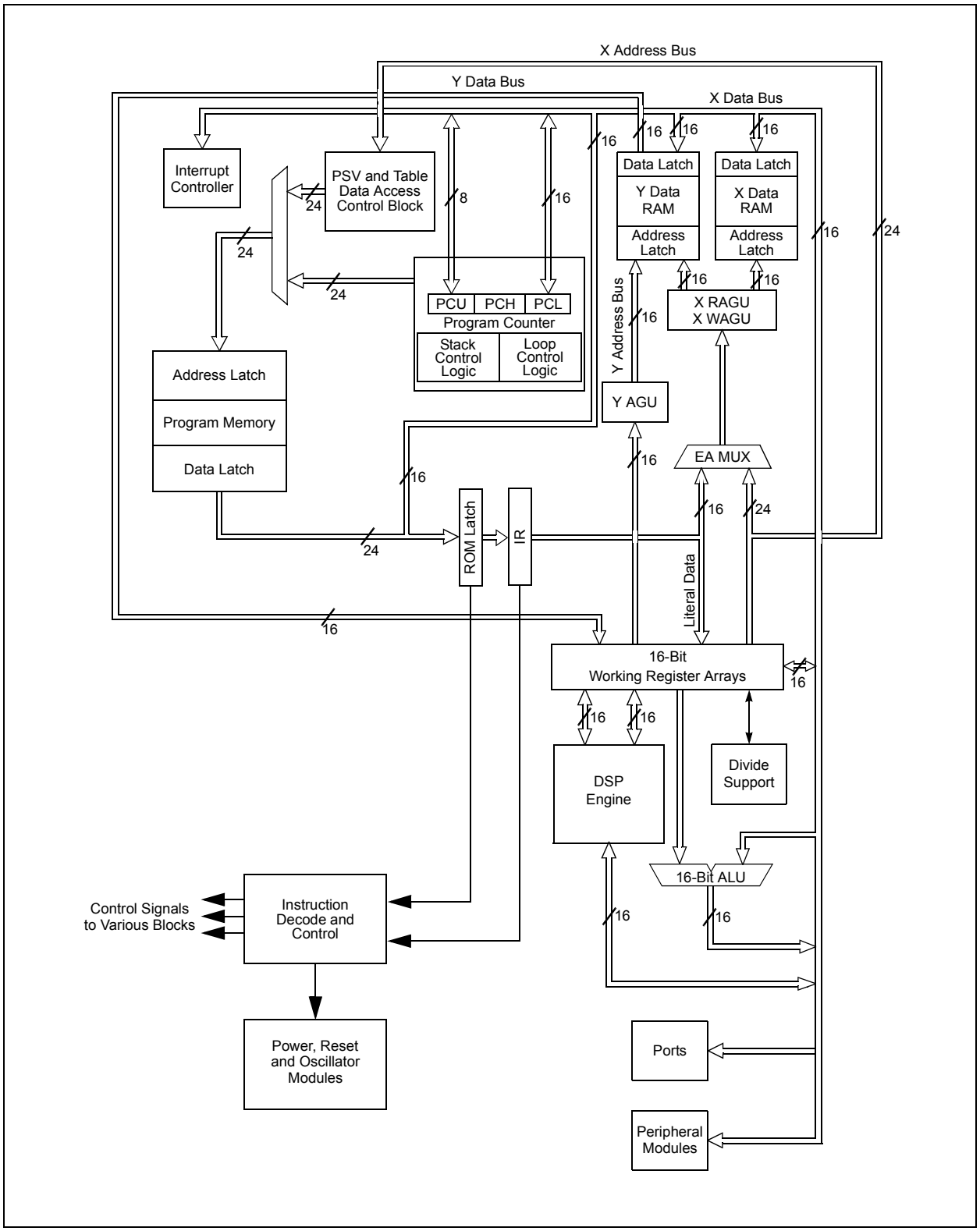
3.4 Addressing Modes

The CPU supports these addressing modes:

- Inherent (no operand)
- Relative
- Literal
- Memory Direct
- Register Direct
- Register Indirect

Each instruction is associated with a predefined addressing mode group, depending upon its functional requirements. As many as six addressing modes are supported for each instruction.

FIGURE 3-1: dsPIC33EPXXGS50X FAMILY CPU BLOCK DIAGRAM



3.5 Programmer's Model

The programmer's model for the dsPIC33EPXXGS50X family is shown in Figure 3-2. All registers in the programmer's model are memory-mapped and can be manipulated directly by instructions. Table 3-1 lists a description of each register.

In addition to the registers contained in the programmer's model, the dsPIC33EPXXGS50X devices contain control registers for Modulo Addressing, Bit-Reversed Addressing and interrupts. These registers are described in subsequent sections of this document.

All registers associated with the programmer's model are memory-mapped, as shown in Table 3-1.

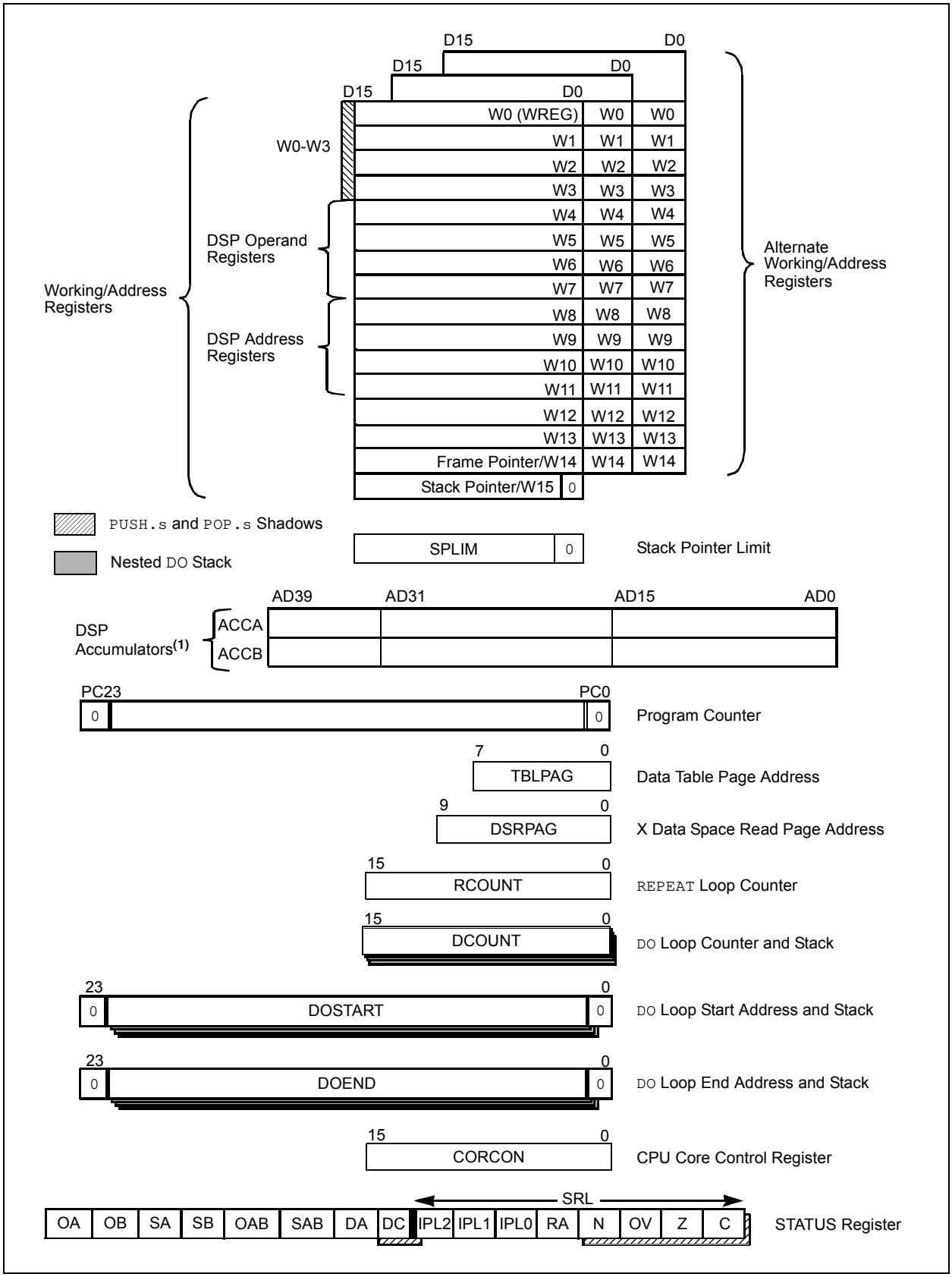
TABLE 3-1: PROGRAMMER'S MODEL REGISTER DESCRIPTIONS

Register(s) Name	Description
W0 through W15(1)	Working Register Array
W0 through W14(1)	Alternate 1 Working Register Array
W0 through W14(1)	Alternate 2 Working Register Array
ACCA, ACCB	40-Bit DSP Accumulators
PC	23-Bit Program Counter
SR	ALU and DSP Engine STATUS Register
SPLIM	Stack Pointer Limit Value Register
TBLPAG	Table Memory Page Address Register
DSRPAG	Extended Data Space (EDS) Read Page Register
RCOUNT	REPEAT Loop Counter Register
DCOUNT	DO Loop Counter Register
DOSTARTH(2), DOSTARTL(2)	DO Loop Start Address Register (High and Low)
DOENDH, DOENDL	DO Loop End Address Register (High and Low)
CORCON	Contains DSP Engine, DO Loop Control and Trap Status bits

Note 1: Memory-mapped W0 through W14 represent the value of the register in the currently active CPU context.

2: The DOSTARTH and DOSTARTL registers are read-only.

FIGURE 3-2: PROGRAMMER'S MODEL



3.6 CPU Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page contains the latest updates and additional information.

3.6.1 KEY RESOURCES

- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools